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ABSTRACT OF THE DISCLOSURE

A method of manufacturing an integrated circuit (IC) stack package device is disclosed. A substrate including multiple dies is processed to form a matrix of dies along separation lines that separate the individual packaged dies. The substrate is formed to have bond pads that correspond to connection pads of the dies. Routers are formed to electrically route a die connection pad to the bottom side of the substrate, which in turn correspond to the wire bond terminal pads of another substrate when stacked vertically. Wire bond contacts are formed from the bond pads on the first side of the substrate die to bond pads on the first side of the substrate. Electrically connected are the routers from the second side of the substrate to the first side of the substrate, thereby the first side bond pads on the second substrate are electrically connected with the connection pads on the second side of the first wafer, forming a stack interconnect configuration. The substrate is separated along the substrate separation zones to produce individualized packaged dies.